



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**Notification# 20160211001  
Datasheet for TRF3765  
Information Only**

**Date:** 2/15/2016  
**To:** Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)).

Sincerely,

PCN Team  
SC Business Services

**Information Only  
Attachments**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
TRF3765IRHBT	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20160211001	<b>PCN Date:</b>	2/15/2016
<b>Title:</b>	Datasheet for TRF3765		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Change Type:</b>			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

### Notification Details

#### Description of Change:

Texas Instruments Incorporated is announcing an information only notification.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.



LM5802

SNVSAA4B –APRIL 2015–REVISED NOVEMBER 2015

#### Changes from Revision B (September 2015) to Revision C

Page

• Changed the documents title from, "UCC28880 700-V Lowest Quiescent Current Off-Line Switcher", to "700-V, 100-mA Low Quiescent Current Off-Line Converter".	1
• Changed <a href="#">Figure 16</a> image.	16
• Changed <a href="#">Equation 14</a> .	19
• Changed <a href="#">Figure 19</a> image.	22
• Changed <a href="#">Figure 22</a> image.	25
• Changed <a href="#">Figure 23</a> image.	25
• Changed <a href="#">Figure 24</a> image.	26
• Changed <a href="#">Figure 25</a> image.	26
• Changed <a href="#">Figure 26</a> image.	27
• Changed <a href="#">Figure 27</a> image.	27
• Changed <a href="#">Figure 28</a> image.	28

#### Changes from Revision A (October 2014) to Revision B

Page

• Added Thermal Shutdown feature.	1
• Changed Applications features.	1
• Changed Power vs Input Voltage image.	1
• Changed Layout Guidelines section.	2
• Changed $T_j$ specification and added note 4, 5 and 6.	4
• Added $I_{VDD}$ ratings.	4
• Added HVIN pin exclusion.	4
• Added VDD clamp voltage specification.	6
• Changed Maximum switch on/off time specification.	6
• Added inductor current run away protection time threshold specification.	6
• Added $R_{THJA}$ vs Copper Area image.	8
• Changed Feature Description section.	10
• Changed PWM Controller section.	13

• Added Current Limit details.....	14
• Changed Figure 15.....	15
• Changed Equation 1.....	15
• Changed Over-Temperature Protection section to Thermal Shutdown section.....	15
• Changed Universal Input, 12-V, 100-mA Output Low-Side Buck image.....	16
• Changed Equation 2.....	17
• Changed.....	17
• Changed Freewheeling Diode (D1) section.....	18
• Changed Equation 5.....	18
• Changed Equation 7.....	19
• Changed Equation 9.....	19
• Changed Equation 10.....	19
• Changed Equation 12.....	19
• Changed Equation 14.....	19
• Changed Equation 17.....	20
• Changed Low-Side Buck-Boost Converter image.....	26
• Changed Layout Guidelines section.....	29

The datasheet number will be changing.

Device Family	Change From:	Change To:
TRF3765	SLWS230D	SLWS230E

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TRF3765>

**Reason for Change:**

To more accurately reflect device characteristics.

**Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):**

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

**Changes to product identification resulting from this PCN:**

None.

**Product Affected:**

TRF3765IRHBR	TRF3765IRHBT
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>